

Title (en)
LAMINATE STRUCTURE FOR A CHIP CARD AND METHOD FOR THE PRODUCTION THEREOF

Title (de)
LAMINATAUFBAU FÜR EINE CHIPKARTE UND VERFAHREN ZU DESSEN HERSTELLUNG

Title (fr)
STRUCTURE STRATIFIÉE POUR UNE CARTE À PUCE ET SON PROCÉDÉ DE FABRICATION

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Application
EP 11707081 A 20110217

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Abstract (en)
[origin: CA2790932A1] The invention relates to a laminate structure (30) for a chip card (31), comprising a base layer (35), a chip module (32) accommodated at least proportionately in the base layer, and at least one cover layer (39) that covers the base layer, wherein an intermediate space (61) formed between the chip module and the cover layer and between the chip module and the base layer is filled with an adhesive material, wherein the adhesive material forms adhesive forces with respect to the wetted surfaces of the base layer and of the cover layer and adhesive forces with respect to the wetted surfaces of the chip module.

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